

.SECTION 27 05 26

GROUNDING & BONDING FOR COMMS

PART 1 - GENERAL

1.1 SUMMARY

- A. Section Includes:
  - 1. Grounding conductors.
  - 2. Grounding connectors.
  - 3. Grounding busbars.
  - 4. Grounding rods.
  - 5. Grounding labeling.

1.2 DEFINITIONS

- A. GEC: Grounding Electrode Conductor (GEC)
- B. TBC: Telecommunications Bonding Conductor.
- C. TEBC: Telecommunications Equipment Bonding Conductor.
- D. TGB: Telecommunications Grounding Busbar.

1.3 ACTION SUBMITTALS

- A. Product Data: For each type of product required for the scope of this project.
- B. Shop Drawings: Indicate locations of grounding features specified including the following:
  - 1. Grounding busbars and routing of their bonding conductors.
  - 2. Ground rods.
  - 3. Ground and roof rings.
  - 4. TEBC, GEC, TMGB, TGBs, and routing of their bonding conductors.
- C. As-Built Data: Plans showing as-built locations of grounding and bonding infrastructure, including the following:
  - 1. Ground rods.
  - 2. Ground and roof rings.
  - 3. TEBC, GEC, TMGB, TGBs, and routing of their bonding conductors.
- D. Field quality-control reports.

1.4 CLOSEOUT SUBMITTALS

- A. Operation and maintenance data.

## 1.5 QUALITY ASSURANCE

- A. Installer Qualifications: Cabling Installer must have personnel certified by BICSI on staff.
  - 1. Field Inspector: Currently registered by BICSI as a designer RCDD to perform the on-site inspection.
  - 2. Installation Supervision: Installation shall be under the direct supervision of ITS Technician, who shall be present at all times when work of this section is performed at Project site.
  - 3. Field Inspector: Currently registered by BICSI as a Registered Communications Distribution Designer (RCDD) to perform the on-site inspection.

## PART 2 - PRODUCTS

### 2.1 GENERAL

- A. All bonding conductors and connectors shall be listed for the purpose intended and approved by a National Recognized Testing Laboratory (NRTL).

### 2.2 SYSTEM DESCRIPTION

- A. Electrical Components, Devices, and Accessories: Listed and labeled as defined in NFPA 70, by a qualified testing agency, and marked for intended location and application.
- B. Comply with UL 467 for grounding and bonding materials and equipment.
- C. Comply with TIA-607-B.

### 2.3 CONDUCTORS

- A. Comply with UL 486A-486B.
- B. Insulated Conductors: Stranded copper wire, green or green with yellow stripe insulation, insulated for 600 V, and complying with UL 83.
  - 1. Ground wire for custom-length equipment ground jumpers shall be a minimum No. 6 AWG, 19-strand, UL-listed, Type THHN wire.
  - 2. Overhead Conveyance Equipment Grounding – Refer to Drawing Details.
- C. Bare Copper Conductors:
  - 1. Solid Conductors: ASTM B 3.
  - 2. Stranded Conductors: ASTM B 8.
  - 3. Tinned Conductors: ASTM B 33.
  - 4. Bonding Cable: 28 kcmils, 14 strand of No. 17 AWG conductor, and 14 inch in diameter.
  - 5. Bonding Conductor: No.4 or No. 6 AWG stranded conductor.
  - 6. Bonding jumper: Tinned-copper tape, braided conductors terminated with two hole copper ferrules, 1-5/8 inches wide and 1/16 inch thick.

## 2.4 CONNECTORS

- A. Irreversible connectors listed for the purpose. Listed by an NRTL as complying with NFPA 70 for specific types, sizes, and combinations of conductors and other items connected. Comply with UL 486A-486B.
- B. Compression Wire Connectors: Crimp-and-compress connectors that bond to the conductor when the connector is compressed around the conductor. Comply with UL 467.
  - 1. Electroplated tinned copper, C and H shaped.
- C. Busbar Connectors: Cast silicon bronze, solderless compression type, mechanical connector; with a long barrel and two holes for a two-bolt connection to the busbar.
- D. Welded Connectors: Exothermic-welding kits of types recommended by kit manufacturer for materials being joined and installation conditions.

## 2.5 GROUNDING BUSBARS

- A. TMGB and TGB: Predrilled, wall-mounted, rectangular bars of hard-drawn solid copper, 1/4 by 4 inches in cross section, length as indicated on Drawings. The busbar shall be NRTL listed for use as TMGB and shall comply with TIA-607-B.
  - 1. Predrilling shall be with holes for use with lugs specified in this Section.
  - 2. Mounting Hardware: Stand-off brackets that provide a 4-inch (100-mm) clearance to access the rear of the busbar. Brackets and bolts shall be stainless steel.
  - 3. Stand-off insulators for mounting shall be Lexan or PVC. Comply with UL 891 for use in 600-V switchboards, impulse tested at 5000 V.
- B. Rack and Cabinet Grounding Busbars: Rectangular bars of hard-drawn solid copper, accepting conductors ranging from No. 14 to No. 2/0 AWG, NRTL listed as complying with UL 467, and complying with TIA-607-B. Predrilling shall be with holes for use with lugs specified in this Section.
  - 1. Cabinet-Mounted Busbar: Terminal block, with stainless-steel or copper-plated hardware for attachment to the cabinet.
  - 2. Rack-Mounted Horizontal Busbar: Designed for mounting in 19-inch equipment racks. Include a copper splice bar for transitioning to an adjoining rack, and stainless-steel or copper-plated hardware for attachment to the rack.

## 2.6 COMPRESSION LUGS

- A. Meets TIA-607-C requirements for network systems grounding applications.
  - 1. Tested by Telcordia – meets NEBS Level 3 with AWG conductor.
- B. UL Listed and CSA Certified with AWG conductor for use up to 35 KV and temperature rated 90°C when crimped with Panduit and specified manufacturers' crimping tools and dies.
- C. Have an "inspection window" over tongue to visually assure full conductor insertion.
- D. Tin-plated to inhibit corrosion.

- E. E. Available with NEMA and BICSI hole size and spacing.
- F. Irreversible connectors listed for the purpose. Listed by an NRTL as complying with NFPA 70 for specific types, sizes, and combinations of conductors and other items connected. Comply with UL 486A-486B.
- G. Compression Type
  - 1. Two holes with various hole spacing to fit the busbar.
  - 2. Long barrel that will allow a minimum of two crimps with standard industry colors.
  - 3. Crimped according to manufacturer's recommendation.
  - 4. Size: 1. #2/0 AWG 2. #6 AWG 3. Material: copper or alloy copper.

## 2.7 LABELING

- A. A. Comply with TIA/EIA-606-B and UL 969 for a system of labeling materials, including label stocks, laminating adhesives, and inks used by label printers.
- B. Adhesive Film Label with Clear Protective Overlay: Machine printed, in black, by thermal transfer or equivalent process. Minimum letter height shall be 3/8 inch.
- C. Overlay shall provide a weatherproof and UV-resistant seal for label.

## 2.8 GROUND RODS

- A. Ground Rods: Copper-clad 3/4 inch in diameter by 10 feet long.

## 2.9 IDENTIFICATION

- A. Comply with requirements for identification products in Section 270553 "Identification for Communications Systems."

## PART 3 - EXECUTION

### 3.1 EXAMINATION

- A. Examine the ac grounding electrode system and equipment grounding for compliance with requirements for maximum ground-resistance level and other conditions affecting performance of grounding and bonding of the electrical system.
- B. Inspect the test results of the ac grounding system measured at the point of BCT connection.
- C. Prepare written report, endorsed by Installer, listing conditions detrimental to performance of the Work.
- D. Proceed with connection of the TBC only after unsatisfactory conditions have been corrected.

### 3.2 INSTALLATION

- A. Bonding shall include the ac utility power service entrance, the communications cable entrance, and the grounding electrode system. The bonding of these elements shall form a loop so that each element is connected to at least two others.
- B. Comply with NECA 1.
- C. Comply with TIA-607-B.

### 3.3 APPLICATION

- A. Conductors: Install solid conductor for No. 8 AWG and smaller and stranded conductors for No. 6 AWG and larger unless otherwise indicated.
  - 1. The bonding conductors between the TGB and structural steel of steel-frame buildings shall not be smaller than No. 6 AWG.
  - 2. The bonding conductors between the TMGB and structural steel of steel-frame buildings shall not be smaller than 2/0 AWG.
- B. Underground Grounding Conductors: Install bare tinned-copper conductor, No. 2 AWG minimum.
- C. Conductor Terminations and Connections:
  - 1. Pipe and Equipment Grounding Conductor Terminations: Bolted connectors.
  - 2. Underground Connections: Welded connectors except at test wells and as otherwise indicated.
  - 3. Connections to Ground Rods at Test Wells: Bolted connectors.
  - 4. Connections to Structural Steel: Welded connectors.
- D. Grounding and Bonding Conductors:
  - 1. Install in the straightest and shortest route between the origination and termination point, and no longer than required. The bend radius shall not be smaller than eight times the diameter of the conductor. No one bend may exceed 90 degrees.
  - 2. Install without splices.
  - 3. Where a grounding and bonding conductor is installed in ferrous metallic conduit, bond the conductor to the conduit using a grounding bushing that complies with requirements in Section 27 05 28 "Pathways for Communications Systems," and bond both ends of the conduit to a TGB.
  - 4. Grounding and bonding conductors shall be in conduit where not routed in a tray system.

### 3.4 GROUNDING ELECTRODE SYSTEM

The BCT between the TMGB and the ac service equipment ground shall not be smaller than No. 3/0 AWG.

### 3.5 GROUNDING BUSBARS

- A. Indicate locations of grounding busbars on Drawings. Install busbars horizontally, on insulated spacers 2 inches minimum from wall, 12 inches above finished floor unless otherwise indicated.

- B. Where indicated on both sides of doorways, route bus up to top of door frame, across top of doorway, and down; connect to horizontal bus.

### 3.6 CONNECTIONS

- A. Bond metallic equipment in a telecommunications equipment room to the grounding busbar in that room, using equipment grounding conductors not smaller than No. 6 AWG.
- B. Stacking of conductors under a single bolt is not permitted when connecting to busbars.
- C. Assemble the wire connector to the conductor, complying with manufacturer's written instructions and as follows:
  1. Use crimping tool and the die specific to the connector.
  2. Pretwist the conductor.
  3. Apply an antioxidant compound to all bolted and compression connections.
- D. Primary Protector: Bond to the TMGB with insulated bonding conductor.
- E. Interconnections: Interconnect all TGBs with the TMGB with the telecommunications backbone conductor. If more than one TMGB is installed, interconnect TMGBs using the grounding equalizer conductor.
- F. Remove paint or finish on all metallic equipment exposing bare metal where bonding connection is made.
- G. Telecommunications Enclosures and Equipment Racks: Bond metallic components of enclosures to the telecommunications bonding and grounding system. Install top-mounted rack grounding busbar unless the enclosure and rack are manufactured with the busbar. Bond the equipment grounding busbar to the TGB No. 2 AWG bonding conductors.
- H. Structural Steel: Where the structural steel of a steel frame building is readily accessible within the room or space, bond each TGB and TMGB to the vertical steel of the building frame.
- I. Electrical Power Panelboards: Where an electrical panelboard for telecommunications equipment is located in the same room or space, bond each TGB to the ground bar of the panelboard.
- J. Shielded Cable: Bond the shield of shielded cable to the TGB in communications rooms and spaces. Comply with TIA-568-C.1 and TIA-568-C.2 when grounding shielded balanced twisted-pair cables.
- K. Rack- and Cabinet-Mounted Equipment: Bond powered equipment chassis to the cabinet or rack grounding bar. Power connection shall comply with NFPA 70; the equipment grounding conductor in the power cord of cord- and plug-connected equipment shall be considered as a supplement to bonding requirements in this Section.
- L. Cable Trays, Basket Trays, and Metallic Conduits: Bond metallic components within the telecommunications space to the telecommunications bonding and grounding system using equipment grounding conductors not smaller than No. 6 AWG.

### 3.7 IDENTIFICATION

- A. Labels shall be preprinted or computer-printed type.
  - 1. Label TMGB(s) with "fs-TMGB," where "fs" is the telecommunications space identifier for the space containing the TMGB.
  - 2. Label TGB(s) with "fs-TGB," where "fs" is the telecommunications space identifier for the space containing the TGB.
  - 3. Label the BCT and each telecommunications backbone conductor at its attachment point: "WARNING! TELECOMMUNICATIONS BONDING CONDUCTOR. DO NOT REMOVE OR DISCONNECT!"
  - 4. Label RGB(s) with "fs-RGB," where "fs" is the telecommunications rack identifier for the rack containing the RGB.
  - 5. Label each end of all grounding conductors with the connected busbar identifier.

### 3.8 FIELD QUALITY CONTROL

- A. Perform tests and inspections.
- B. Tests and Inspections:
  - 1. Inspect physical and mechanical condition. Verify tightness of accessible, bolted, electrical connections with a calibrated torque wrench according to manufacturer's written instructions.
  - 2. Test the bonding connections of the system using an ac earth ground-resistance tester, taking two-point bonding measurements in each telecommunications equipment room containing a TMGB and a TGB and using the process recommended by BICSI TDMM. Conduct tests with the facility in operation.
    - a. Measure the resistance between the busbar and the nearest available grounding electrode. The maximum acceptable value of this bonding resistance is 100 milliohms.
    - b. Test for ground loop currents using a digital clamp-on ammeter, with a full-scale of not more than 10 A, displaying current in increments of 0.01 A at an accuracy of plus/minus 2.0 percent.
    - c. With the grounding infrastructure completed and the communications system electronics operating, measure the current in every conductor connected to the TMGB and in each TGB. Maximum acceptable ac current level is 1 A.
- C. Grounding system will be considered defective if it does not pass tests and inspections.
- D. Prepare test and inspection reports.

END OF SECTION 27 05 26